

OL-SA58672UK

Wafer level chip-size package; 9 bumps; 1.66 X 1.71 X 0.6 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | WLCSP |
| Package type industry code | WLCSP |
| Package style descriptive code | UC (uncased chip) |
| Package style suffix code | NA (not applicable) |
| Package body material type | X (other) |
| Mounting method type | S (surface mount) |
| Issue date | 12-6-2008 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-------|------|------|
| D | package length | 1.63 | - | 1.66 | 1.69 | mm |
| E | package width | 1.68 | - | 1.71 | 1.74 | mm |
| A | seated height | [tbd] | - | [tbd] | 0.64 | mm |
| A ₂ | package height | 0.34 | - | 0.36 | 0.38 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 9 | - | |



2. Package outline

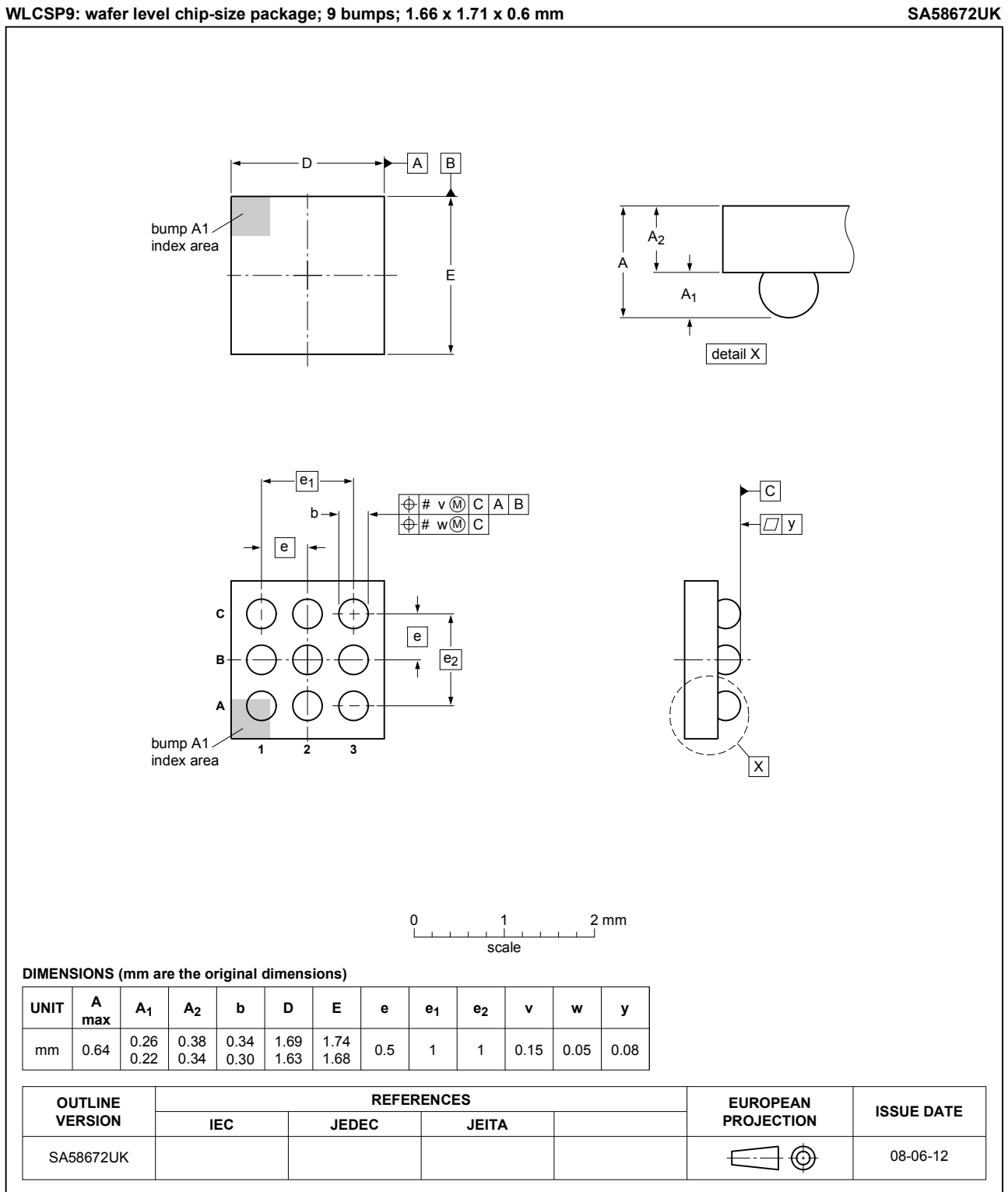


Fig. 1. Package outline WLCSP (OL-SA58672UK)

3. Legal information

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